

METHOD OF SECURING A SUBSTRATE IN A SEMICONDUCTOR PROCESSING MACHINE

Abstract of the Disclosure:

A method of securing a substrate in a semiconductor processing machine. The method includes moving latch bodies between latched and unlatched positions while permitting contact between a clamping member of each latch body and the substrate only if the latch

5 bodies are substantially in the latched position. In the latched position, the clamping members apply a clamping force effective to secure the substrate. Generally, contact is prevented by engagement between a support member and an ramp that is inclined such that the clamping member descends toward the substrate as the latch body moves from the unlatched position to the latched position and only contacts the substrate as the latched position is established.